

SYSTEM AND METHOD FOR ALIGNING AN INTEGRATED  
CIRCUIT DIE ON AN INTEGRATED CIRCUIT SUBSTRATE

ABSTRACT OF THE DISCLOSURE

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10 A system and method is disclosed for aligning an  
integrated circuit die on an integrated circuit substrate.  
A plurality of deposits of deformable material are placed  
on the substrate where the integrated circuit die is to be  
aligned. In one advantageous embodiment a stamping tool is  
indexed to a first tooling hole and to a second tooling  
hole in the substrate. The stamping tool imprints the  
deposits of deformable material to a tolerance of less than  
one hundred microns with respect to the first and second  
tooling holes. The imprinted portions of the deposits to  
form a pocket for receiving the integrated circuit die.  
This enables the integrated circuit die to be precisely  
aligned on the substrate in three dimensions.